



Pb Free Plating Product

## MB22S thru MB210S

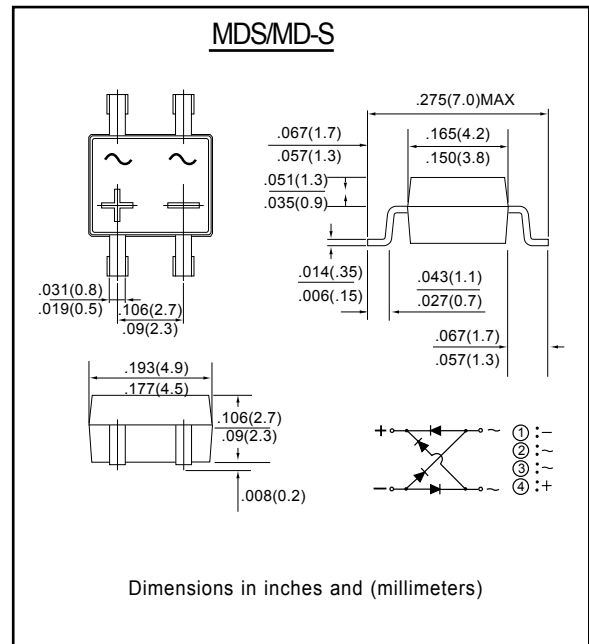
2.0 Ampere Surface Mount MDS/MD-S Schottky Bridge Rectifiers

### Features

- ◆ Schottky barrier rectifier diode chip package device
- ◆ Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- ◆ High surge overload rating:30A peak
- ◆ Saves space on printed circuit boards
- ◆ High temperature soldering guaranteed:260 °C/10 seconds

### Mechanical Data

- ◆ Case:Molded plastic body MDS/MD-S Package
- ◆ Terminals: plated leads solderable per MIL-STD-750, Method 2026
- ◆ Mounting Position:Any
- ◆ Weight:0.078 oz.,0.22g



### Maximum Ratings & Electrical Characteristics (T<sub>A</sub>=25 °C unless otherwise noted)

Parameter	Symbol	MB22S	MB24S	MB26S	MB28S	MB210S	Unit
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	20	40	60	80	100	V
Maximum RMS voltage	V <sub>RMS</sub>	14	28	42	56	70	V
Maximum DC blocking voltage	V <sub>DC</sub>	20	40	60	80	100	V
Maximum Average forward output current	I <sub>F(AV)</sub>	2.0					A
Peak forward surge current 8.3 MS single HALF sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	50					A
Maximum instantaneous forward voltage at 2 OA	VF	0.55		0.70		0.85	V
Maximum DC reverse current at Ta=25 °C rated DC blocking voltage per leg Ta=100 °C	IR	0.5 20					mA
Typical thermal resistance per leg(Note1)	R <sub>θJA</sub> R <sub>θJL</sub>	80 20					°C/W
Operation junction temperature range	T <sub>J</sub>	-55 to +125					°C
Storage temperature range	T <sub>STG</sub>	-55 to +150					°C

**Notes:** 1. Thermal resistance from junction to ambient and from junction to lead P.C B. mounted on 0.2x0.2" (5.0x5.0mm) copper pad areas.

## RATINGS AND CHARACTERISTIC CURVES

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

FIG. 1 - FORWARD CURRENT DERATING CURVE

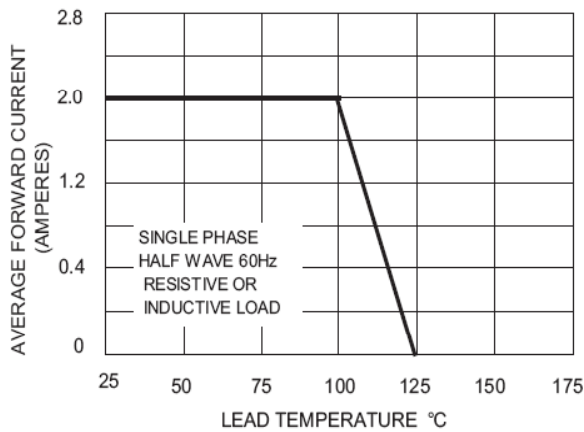


FIG. 2 - MAXIMUM NON-REPETITIVE SURGE CURRENT

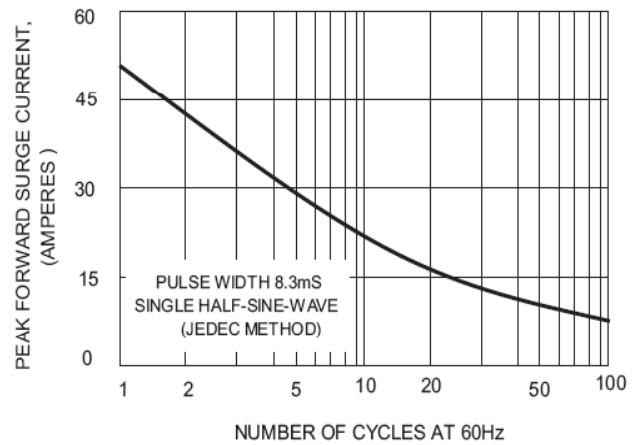


FIG.3-TYPICAL FORWARD CHARACTERISTICS

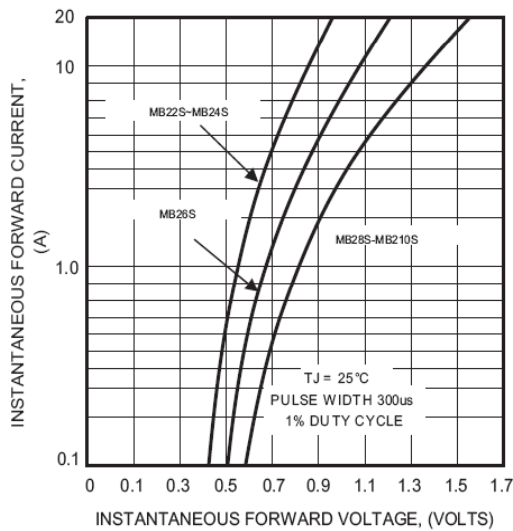


FIG.5-TYPICAL REVERSE CHARACTERISTICS

